



Product code : 50040B

ISOLEMFI 50040B MONO

DESCRIPTION

ISOLEMFI 50040B MONO is a one-part polyurethane-based moisture curing adhesive

AREAS OF APPLICATION

ISOLEMFI 50040B MONO may be used for bonding of hard insulating foams like extruded or expanded polystyrene and phenolic foam or of panels from mineral wool on wood, plaster boards (with or without vapour shield), fibre-cement for production of partition walls and thermal insulation elements.

ISOLEMFI 50040B MONO is not recommended for bonding onto metal.

TECHNICAL DATA

Appearance	Thixotropic paste
Colour	Cream, translucent
Viscosity at 20 °C	Brookfield RVT / spindle 7 / 5 rpm : 400,000 ± 100,000 mPa.s
Density at 20 °C	1.05 ± 0.02
Conventional solids content (EN 827)	100 %
Open time at 20 °C	Ca 3 min (at 50 % HR)
Pressing time at 20 °C	30 min (at 50 % HR)
Final setting time at 20 °C	24 h
Temperature resistance of the assemblies	-30 to +100 °C
Cleaner	EMFINET 683 before setting
Specific data	Water resistance : very good

ADVICE

See also material safety data sheet



INSTRUCTIONS FOR USE

Substrates preparation :

The substrates to be assembled must be flat, dry, dust free and not have any traces of grease or other contaminants that could adversely affect the bonding performance.

If the substrates need to be cleaned, EMFINET 683 or methylethylketone (MEK) may be used. The use of solvents must comply with local regulations. Check the compatibility of the solvent used with the substrates.

Note : when using solvents, extinguish all sources of ignition and carefully follow the safety and handling instructions given by the manufacturer or supplier.

Application :

The adhesive is applied in strips on one of the substrates by a gun for cartridges or with a spreader.

One of the materials to be bonded must be porous or contain moisture. If both substrates are non porous, it is imperative to spray a light water mist (10 to 15 g/m²) onto the adhesive film.

Assembling has to be followed by a uniform and maximum pressure applied across the entire surface without irreversible deformation of substrates.

The setting time depends on hygrometry and temperature. So it is necessary :

- in case of working under 20 °C : to be sure that pressing time is long enough
- in case of working over 20 °C : to be sure that open time and closed assembly time are not excessive

Otherwise, defective bonding could happen.

If necessary, refer to our technical service.

Cleaning :

Tools can be cleaned with EMFINET 683 or MEK before the adhesive has completely cured. After curing, abrasion is necessary.

CONSUMPTION

150 to 250 g/m² according to the method of application and the materials to be bonded

STORAGE AND SHELF LIFE

12 months in closed original packaging stored in dry premises between 5 and 25 °C

PACKAGING

310 ml PE cartridges

200 kg metallic drums

SAFETY

Harmful. See material safety data sheet before use.

The technical data contained herein is based on our present knowledge and experience and we cannot be held liable for any errors, inaccuracies, omissions or editorial failings that result from technological changes or research between the date of issue of this document and the date the product is acquired.

Before using the product, the user should carry out any necessary tests in order to ensure that the product is suitable for the intended application. Moreover, all users should contact the seller or the manufacturer of the product for additional technical information concerning its use if they think that the information in their possession needs to be clarified in any way, whether for normal use or a specific application of our product.

Our guarantee applies within the context of the statutory regulations and provisions in force, current professional standards and in accordance with the stipulations set out in our general sales conditions.

The information detailed in the present technical data sheet is given by way of indication and is not exhaustive. The same applies to any information provided verbally by telephone to any prospective or existing customer.